

P-Channel Enhancement Mode Power MOSFET

Description

The JTD2216 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

General Features

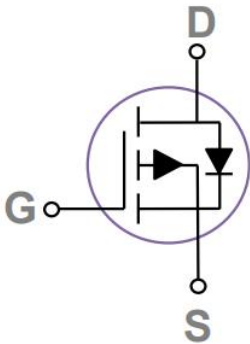
$V_{DS} = -20V$

$I_D = -16A$

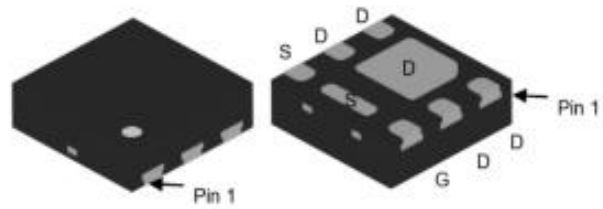
$R_{DS(ON)} : 12.5m\Omega$ (Typ.) @ $V_{GS} = -4.5V$

$R_{DS(ON)} : 16.1m\Omega$ (Typ.) @ $V_{GS} = -2.5V$

Schematic diagram



SOT23-3 Pin Assignment



Top View

Bottom View

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	-20	V	
Gate-Source Voltage	V_{GS}	± 12	V	
Drain Current-Continuous	I_D	$T_A = 25^\circ C$	-16	A
		$T_A = 100^\circ C$	-10	A
Pulsed Drain Current ^(Note 1)	I_{DM}	-30	A	
Maximum Power Dissipation	P_D	2.3	W	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C	

Thermal Characteristics

Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{th JA}$	49	°C/W
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Electrical Characteristics (TA=25°C unless otherwise noted)

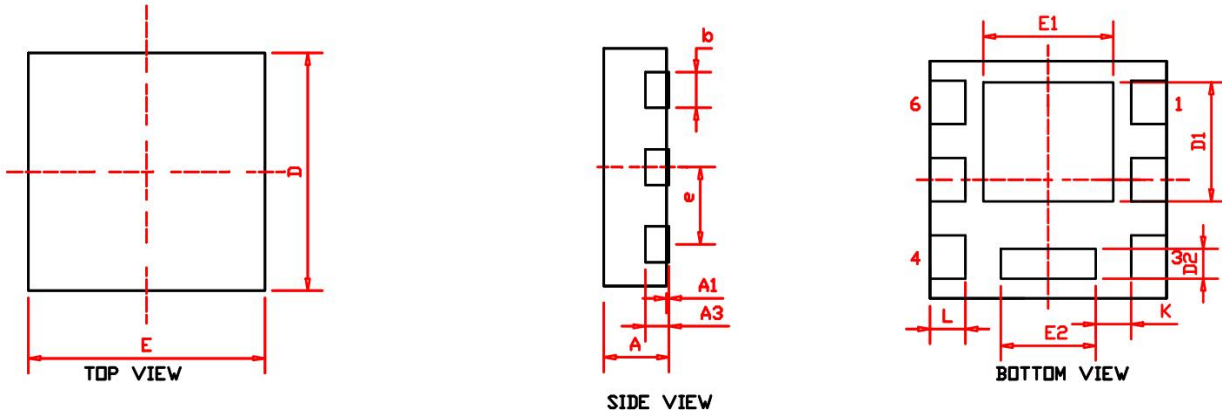
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	-20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20V, V_{GS}=0V$	-	-	-1	μA
Gate-Body Leakage	I_{GSS}	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	-0.4	-0.68	-1.0	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=-8A$	-	12.5	17.3	m Ω
		$V_{GS}=2.5V, I_D=-5A$	-	16.1	23	
Forward Transconductance	g_{FS}	$V_{DS}=-5V, I_D=-5A$	-	5	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{ISS}	$V_{DS}=-6V, V_{GS}=0V$ $f=1.0MHz$	-	1280	-	pF
Output Capacitance	C_{OSS}		-	300	-	pF
Reverse Transfer Capacitance	C_{RSS}		-	280	-	pF
Switching Characteristics						
Turn-On Delay Time	$t_{D(ON)}$	$V_{DD} = -10V$ $R_L = 10 \Omega$ $I_D = -2.8A,$ $V_{GEN} = -4.5V$ $R_G = 6 \Omega$	-	15	-	ns
Rise Time	t_r		-	60	-	ns
Turn-Off Delay Time	$t_{D(OFF)}$		-	70	-	ns
Fall Time	t_f		-	65	-	ns
Total Gate Charge	Q_g	$V_{DS}=-10V, I_D=-5A,$ $V_{GS}=-4.5V$	-	14	-	nC
Gate-Source Charge	Q_{gs}		-	3	-	nC
Gate-Drain Charge	Q_{gd}		-	3.5	-	nC
Drain-Source Diode Characteristics ^(Note 3)						
Diode forward voltage	V_{SD}	$V_{GS}=0V, I_S=-1.25A$		-0.72	-1.2	V

Notes

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10sec$.
3. Pulse Test: PulseWidth $\leq 300\mu S$, Duty Cycle $\leq 2\%$
4. Guaranteed by design, not subject to production testing.

Package Information

DFN2X2-6



PACKAGE TYPE			
SYMBOLS	MIN	NOM	MAX
A	0.60	-	0.80
A1	0.000	0.02	0.050
A3	0.203 REF		
b	0.30	0.35	0.40
D	1.924	2.0	2.076
E	1.924	2.0	2.076
e	0.650 TYP		
L	0.224	0.30	0.376
K	0.20	-	-
E1	1.00	1.10	1.20
D1	0.90	1.00	1.10
E2	0.50	0.70	0.90
D2	0.20	0.30	0.35